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HITB ★ V04 88-128666/19 ★ J6 3070-486-A
Electroless copper plating on copper-clad laminates by mounting laminates on jig and replacing one sheet with palladium-catalyst absorbing base plate.

HITACHI CHEMICAL KK 11.09.88-JP-214536
L03 M13 (30.03.88) C23c-18/38 H05k-03/18

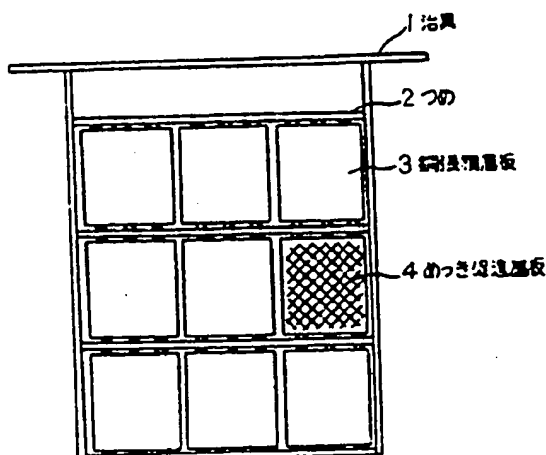
11.09.88 as 214536 (93HW)

The laminates having more than one sheet perforated on the jig are mounted to give a planar form, where one piece of sheet among the laminates is replaced by a base plate to which Pd-catalyst is adsorbed well, and is mounted on the jig, making each mounted plate electrically conductive.

USE - With the method, electroless Cu plating can be applied to a number of perforated Cu-clad laminates efficiently. (3pp

Dwg.No.1/1)
 N88-097753

V4-R2A



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